



HMPSA43

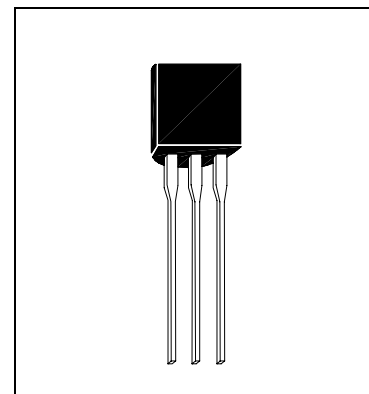
NPN SILICON TRANSISTOR

Description

The HMPSA43 is high voltage transistor.

Features

- High Collector-Emitter Breakdown Voltage
- Low Collector-Emitter Saturation Voltage
- For Complementary Use with PNP Type HMPSA93



Absolute Maximum Ratings

- Maximum Temperatures
Storage Temperature -55 ~ +150 °C
Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Ta=25°C) 625 mW
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage 200 V
VCEO Collector to Emitter Voltage 200 V
VEBO Emitter to Base Voltage 6 V
IC Collector Current 500 mA

Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCBO	200	-	-	V	IC=100uA, IE=0
BVCEO	200	-	-	V	IC=1mA, IB=0
BVEBO	6	-	-	V	IE=10uA, IC=0
ICBO	-	-	100	nA	VCB=200V, IE=0
IEBO	-	-	100	nA	VEB=6V, IC=0
*VCE(sat)	-	-	350	mV	IC=20mA, IB=2mA
*VBE(sat)	-	-	900	mV	IC=20mA, IB=2mA
*hFE1	25	-	-		IC=1mA, VCE=10V
*hFE2	40	-	-		IC=10mA, VCE=10V
*hFE3	40	-	-		IC=30mA, VCE=10V
fT	50	-	-	MHz	IC=10mA, VCE=20V, f=100MHZ
Cob	-	-	4	pF	VCB=20V, f=1MHz

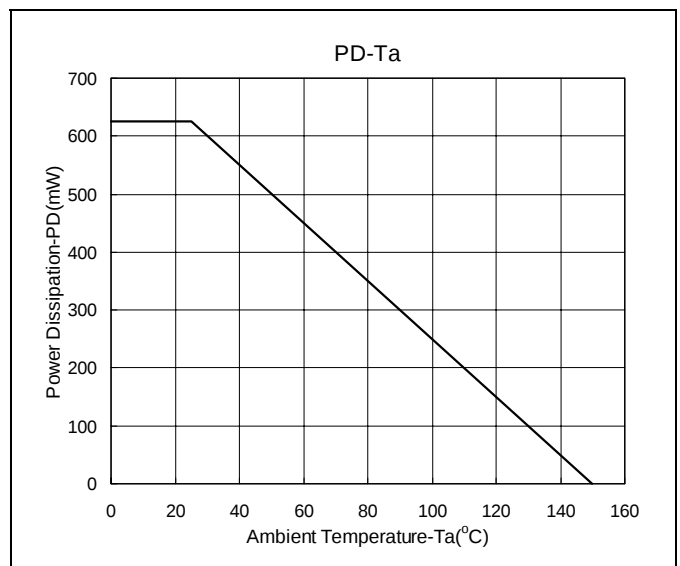
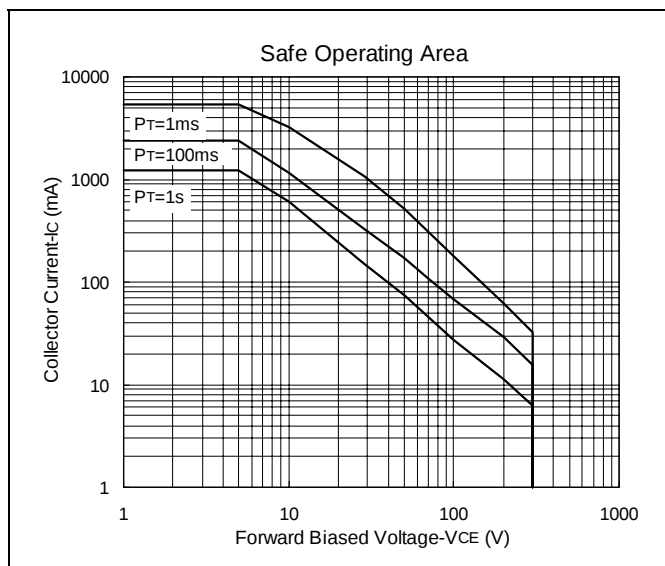
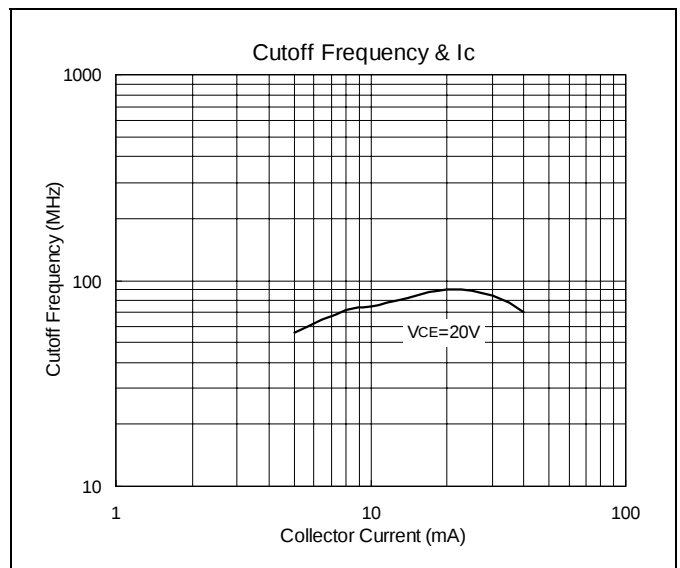
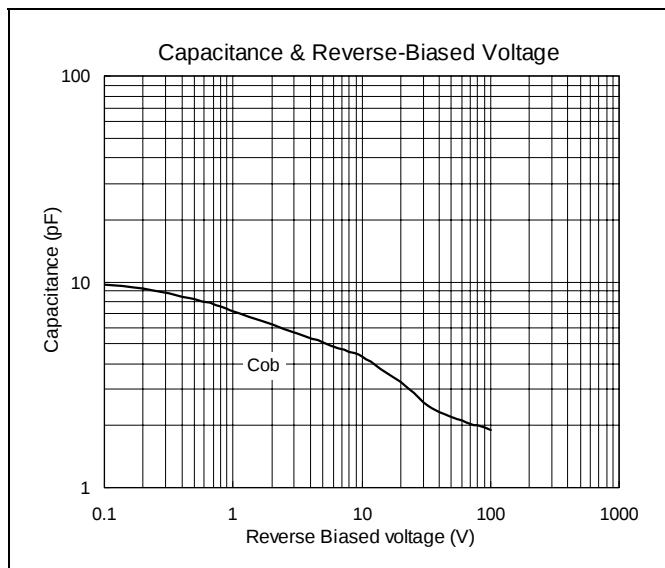
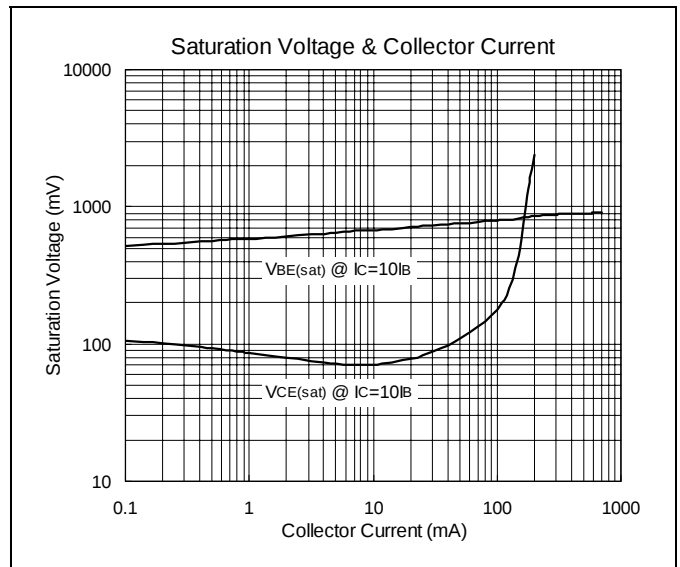
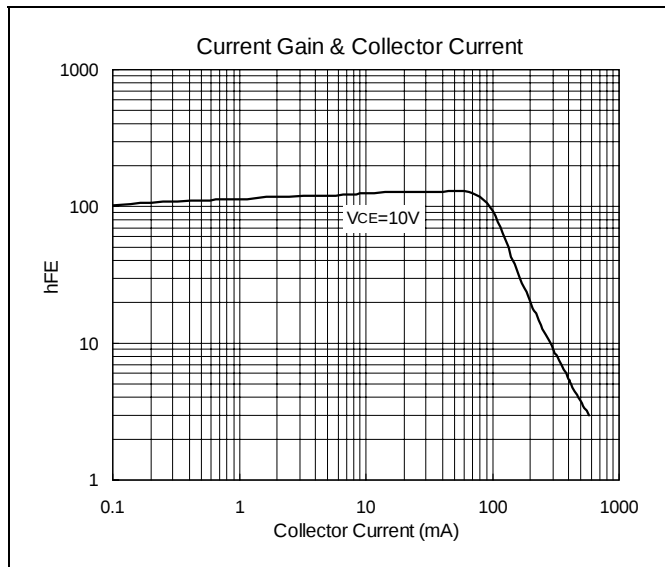
*Pulse Test : Pulse Width ≤380us, Duty Cycles≤2%

Classification Of hFE2 & VCE(sat)

Rank	hFE1	hFE2	hFE3	VCE(sat)
NS	>80	>120	>120	<200mV
N	>25	>40	>40	<350mV

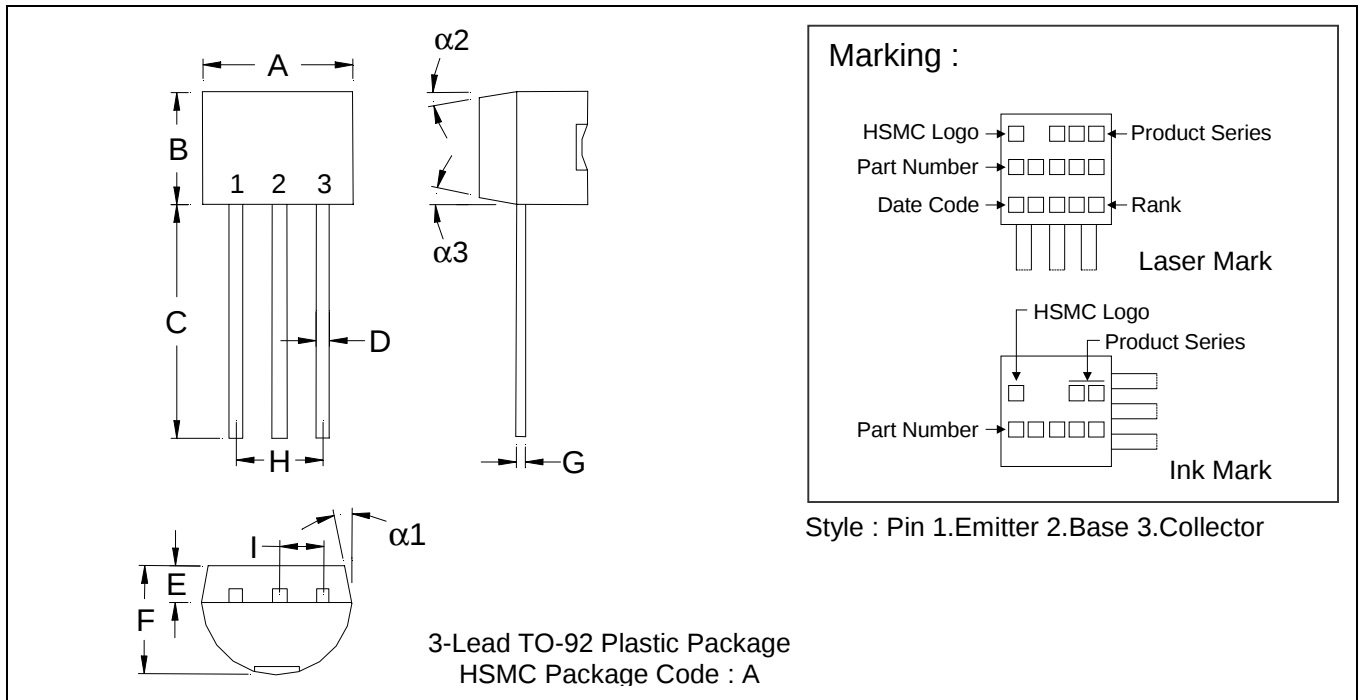


Characteristics Curve





TO-92 Dimension



*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	α1	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	α2	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	α3	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.

2.Controlling dimension : millimeters.

3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.

4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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